

45th IEEE Semiconductor Interface **Specialists Conference**



Bahia Resort Hotel, San Diego, CA December 10–13, 2014 (Tutorial: December 10) www.ieeesisc.org



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Call for Papers

The SISC is a workshop-style conference that provides a forum for device engineers, solid state physicists, and materials scientists to discuss topics of common interest, formally through invited and contributed presentations, and informally during various events including a poster presentation session. The SISC is sponsored by the IEEE Electron Devices Society, and will be held immediately prior to the IEEE IEDM.

The program includes talks (theory and experiment) from all areas of MOS science and technology, including but not limited to:

- SiO2 and high-k gate dielectrics on Si and their interfaces.
- Insulators on high-mobility and alternative substrates (SiGe, Ge, III-V and III-N, SiC, etc.)
- MOS gate stacks with metal gate electrodes
- Stacked dielectric layers for non-volatile memory
- Oxide and interface structure, chemistry, defects, and passivation: Theory and experiment
- Electrical characterization, performance and reliability of MOS-based devices
- Surface cleaning technology and impact on dielectrics and interfaces
- Dielectrics on nanowires/-tubes and graphene
- Oxide electronics and multiferroics
- Interfaces in photovoltaics, e.g. Si passivation
- **2D materials and devices** and their interfaces

Invited speakers

Prof. Kevin Chen, Hong Kong University of Science and Technology, Hong Kong

Dielectric/III-N Interfaces with Nitridation Interlayer for GaN Power Electronics

Dr. Luigi Colombo, Texas Instruments, USA 2D Materials Growth and Prospects

Dr. Jacopo Franco, imec, Belgium

Reliability challenges of high mobility channel technologies: SiGe, Ge and InGaAs

Prof. Roy Gordon, Harvard University, USA

Single-crystal oxide insulators grown epitaxially on GaAs, Ge and GaN by ALD Dr. Jan Van Houdt, imec, Belgium

Memory technologies for the terabit era: a paradigm shift

Prof. Ali Javey, UC Berkeley, USA

Contact engineering, chemical doping and heterostructures of layered chalcogenides

Dr. Sergei V. Kalinin, Oak Ridge National Lab, USA

In-situ probing surfaces of oxide electronic materials with atomic resolution: physical functionalities and memristive mechanisms

Prof. Kousuke Nagashio, Univ. of Tokyo, Japan

Carrier response in electric-field-induced bandgap of bilayer graphene

- Dr. Tun-Wen Pi, National Synchrotron Radiation Research Center, Taiwan High k oxides on (In)GaAs surfaces studied by synchrotron radiation photoemission
- Prof. Thomas Schroeder, IHP (Frankfurt/Oder), Germany

From global and local Ge integration approaches on Si(001): Novel insights by advanced synchrotron XRD techniques

Prof. Max Di Ventra, UCSD, USA

Memcomputing: computing with and in memory

Prof. Ken Uchida, Keio University, Japan

Evaluation of thermal properties of nanoscale MOSFETs and thermal aware device design of nano devices

Wednesday evening Tutorial – free to all registered SISC attendees

Dr. Perrine Batude, CEA-LETI, France

3D monolithic integration: an alternative path towards CMOS scalability

A Best Student Presentation Award will be given in memory of E.H. Nicollian.

Deadline for Receipt of Extended Abstracts: August 11, 2014

Abstract submission, previous technical programs, contact information, etc.: http://www.ieeesisc.org